The Claims:

Please provisionally withdraw claims 29 and 30 from consideration, with traverse.

Listing of Claims:

Claims 1-13 : Previously Canceled.

14. (previously presented) A method for making microcomponents exhibiting microreliefs of an optical quality, comprising:

making microrelief of an optical quality for each microcomponent by mechanical machining of the substrate, the mechanical machining comprising moving at least one tool translationally and parallel to the substrate, the mechanical machining not carried out through the thickness of the substrate; and

cutting out the microcomponents in the substrate such that the individual microcomponents or groups of microcomponents are separated from each other.

15. (previously presented) A method according to Claim 14, wherein the first mechanical machining step comprises at least two substeps: a first substep for blank-forming and a second substep for finishing.

16. (previously presented) A method according to Claim 14, wherein making a microrelief is performed to an extent of the microrelief being optically polished.

17. (previously presented) A method according to Claim 14, wherein the microrelief is made with a single tool moved at the surface of the substrate.

18. (previously presented) A method according to Claim 14, wherein the microrelief is made by several tools working simultaneously and/or in succession.

19. (previously presented) A method according to Claim 14, wherein the microrelief is made with a saw moved along one direction at a time.

20. (previously presented) A method according to Claim 14, wherein the microcomponents are microprisms.

21. (previously presented) A method according to Claim 14, wherein the mocroprisms are made by a "V" profile abrasive blade.

22. (previously presented) A method according to Claim 19, the saw having a blade with plane and parallel faces, or having at least an inclined face.

23. (previously presented) A method according to Claim 14, wherein making a microrelief consists of passing a blade having a die which does not have abrasive grit therein, said blade being used as carrier for a separate polishing abrasive distributed in the microreliefs.

24. (previously presented) A method according to Claim 14, wherein making a microrelief further comprises performing surface chemical etching of the substrate.

25. (previously presented) A method according to Claim 14, wherein making a microrelief further comprises forming a planarizing coating on the substrate.

26. (previously presented) A method according to Claim 14, wherein making a microrelief comprises using a "U" shaped blade having side portions comprising first abrasive grits and an end portion comprising second abrasive grits, the second abrasive grits being of a larger particle size than the first abrasive grits.

27. (previously presented) A method for making microcomponents exhibiting microreliefs of an optical quality, comprising:

making a relief of optical quality for each microcomponent by mechanical machining of the substrate, the mechanical machining comprising moving at least

one tool translationally and parallel to the substrate, the vertical dimension of the microrelief being in the range between 10 microns to 600 microns; and

cutting out the microcomponents in the substrate such that the individual microcomponents or groups of microcomponents are separated from each other.

28. (previously presented) A method of making a microcomponent in a substrate of a certain thickness, the method comprising:

mechanically machining, by moving at least one tool translationally relative to the material, a microcomponent in the substrate;

producing, as a result of the mechanically machining, an optical quality surface on a microrelief scale in the substrate;

separating the microcomponent from the remainder of the substrate.

29. (Withdrawn) A method of making microcomponent in a material of a certain thickness, the method comprising:

removing material on a microrelief scale from the substrate, the removal of material not exceeding the thickness of the material, the removal performed in a translational relationship to the substrate;

producing, based on the step of removing material, a microrelief feature in the material having a surface of optical quality.

30. (Withdrawn) A method of making a microcomponent in a material of certain thickness, the method comprising:

removing material from the substrate, the removal of material not exceeding the thickness of the material, the removal performed in a translational relationship to the substrate;

producing, based on the step of removing material, a feature in the material having a surface of optical quality, the vertical dimension of the relief in the material being between 10 microns and 600 microns.